## $\mathcal{N}_{\varepsilon \omega} \mathcal{I}_{\varepsilon r s \varepsilon y} S_{\varepsilon m i-C o n d u c t o r} \mathfrak{P}_{\text {roduct }}, I_{n c}$.

## FEATURES

- High power gain
- Easy power control
- Good thermal stability
- Gold metallization ensures excellent reliability.


## APPLICATIONS

- Broadcast transmitters in the VHF frequency range.


## DESCRIPTION

Dual push-pull silicon N -channel enhancement mode vertical D-MOS transistor encapsulated in a 4-lead, SOT262A1 balanced flange package with two ceramic caps. The mounting flange provides the common source connection for the transistors.

| CAUTION |
| :--- |
| This product is supplied in anti-static packing to prevent <br> damage caused by electrostatic discharge during <br> transport and handling. |

PINNING - SOT262A1

| PIN | DESCRIPTION |
| :---: | :--- |
| 1 | drain 1 |
| 2 | drain 2 |
| 3 | gate 1 |
| 4 | gate 2 |
| 5 | source |



Fig. 1 Simplified outline and symbol.

## QUICK REFERENCE DATA

RF performance at $\mathrm{T}_{\mathrm{h}}=25^{\circ} \mathrm{C}$ in a push-pull common source test circuit.

| MODE OF OPERATION | $\mathbf{f}$ <br> $(\mathbf{M H z})$ | $\mathbf{V}_{\mathbf{D S}}$ <br> $(\mathbf{V})$ | $\mathbf{P}_{\mathbf{L}}$ <br> $(\mathbf{W})$ | $\mathbf{G}_{\mathbf{p}}$ <br> $(\mathrm{dB})$ | $\eta_{\mathbf{D}}$ <br> $(\%)$ |
| :--- | :---: | :---: | :---: | :---: | :---: |
| CW, class-B | 108 | 50 | 300 | $>20$ | $>60$ |
| CW, class-C | 108 | 50 | 300 | typ. 18 | typ. 80 |
| CW, class-AB | 225 | 50 | 250 | $>14$ <br> typ. 16 | $>50$ <br> typ. 55 |


| WARNING |
| :--- |
| Product and environmental safety - toxic materials |
| This product contains beryllium oxide. The product is entirely safe provided that the BeO discs are not damaged. |
| All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety |
| precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of |
| the user. It must never be thrown out with the general or domestic waste. |

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## LIMITING VALUES

In accordance with the Absolute Maximum System (IEC 60134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Per transistor section |  |  |  |  |  |
| $\mathrm{V}_{\mathrm{DS}}$ | drain-source voltage |  | - | 125 | V |
| $\mathrm{V}_{\mathrm{GS}}$ | gate-source voltage |  | - | $\pm 20$ | V |
| $\mathrm{I}_{\mathrm{D}}$ | drain current (DC) |  | - | 18 | A |
| $\mathrm{P}_{\text {tot }}$ | total power dissipation | $\mathrm{T}_{\text {mb }} \leq 25^{\circ} \mathrm{C}$; total device; both sections equally loaded | - | 500 | W |
| $\mathrm{T}_{\text {stg }}$ | storage temperature |  | -65 | 150 | ${ }^{\circ} \mathrm{C}$ |
| T | junction temperature |  | - | 200 | ${ }^{\circ} \mathrm{C}$ |

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
| :--- | :--- | :--- | :---: | :---: |
| $R_{\mathrm{th} j-\mathrm{mb}}$ | thermal resistance from junction <br> to mounting base | total device; both sections <br> equally loaded. | max. 0.35 | K/W |
| $R_{\mathrm{th} \text { mb-h }}$ | thermal resistance from <br> mounting base to heatsink | total device; both sections <br> equally loaded. | max. 0.15 | K/W |



Total device; both sections equally loaded.
(1) Current is this area may be limited by $\mathrm{R}_{\mathrm{DSon}}$.
(2) $\mathrm{T}_{\mathrm{mb}}=25^{\circ} \mathrm{C}$.

Fig. 2 DC SOAR.


Total device; both sections equally loaded.
(1) Continuous operation.
(2) Short-time operation during mismatch.

Fig. 3 Power derating curves.

## CHARACTERISTICS

$\mathrm{T}_{\mathrm{j}}=25^{\circ} \mathrm{C}$ unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Per transistor section |  |  |  |  |  |  |
| $\mathrm{V}_{\text {(BR) }}$ DSs | drain-source breakdown voltage | $V_{G S}=0 ; l_{D}=100 \mathrm{~mA}$ | 125 | - | - | V |
| loss | drain-source leakage current | $V_{G S}=0 ; V_{D S}=50 \mathrm{~V}$ | - | - | 2.5 | mA |
| Gss | gate-source leakage current | $\mathrm{V}_{\mathrm{GS}}= \pm 20 \mathrm{~V} ; \mathrm{V}_{\mathrm{DS}}=0$ | - | - | 1 | $\mu \mathrm{A}$ |
| $\mathrm{V}_{\mathrm{GSth}}$ | gate-source threshold voltage | $V_{D S}=10 \mathrm{~V} ; l_{\text {d }}=50 \mathrm{~mA}$ | 2 | - | 4.5 | V |
| $\Delta V_{G S}$ | gate-source voltage difference of both sections | $V_{D S}=10 \mathrm{~V} ; \mathrm{l}_{\mathrm{D}}=50 \mathrm{~mA}$ | - | - | 100 | mV |
| $\mathrm{g}_{\mathrm{fs}}$ | forward transconductance | $V_{D S}=10 \mathrm{~V} ; \mathrm{l}_{\mathrm{D}}=5 \mathrm{~A}$ | 4.5 | 6.2 | - | S |
| $\mathrm{g}_{\mathrm{fs} 1} / \mathrm{g}_{\mathrm{f} 2}$ | forward transconductance ratio of both sections | $V_{D S}=10 \mathrm{~V} ; \mathrm{l}_{\mathrm{D}}=5 \mathrm{~A}$ | 0.9 | - | 1.1 |  |
| R ${ }_{\text {DSon }}$ | drain-source on-state resistance | $V_{G S}=10 \mathrm{~V} ; \mathrm{l}_{\mathrm{D}}=5 \mathrm{~A}$ | - | 0.2 | 0.3 | $\Omega$ |
| losx | drain cut-off current | $\mathrm{V}_{\mathrm{GS}}=10 \mathrm{~V} ; \mathrm{V}_{\mathrm{DS}}=10 \mathrm{~V}$ | - | 25 | - | A |
| $\mathrm{C}_{\text {is }}$ | input capacitance | $V_{G S}=0 ; V_{D S}=50 \mathrm{~V} ; \mathrm{f}=1 \mathrm{MHz}$ | - | 480 | - | pF |
| $\mathrm{C}_{\mathrm{OS}}$ | output capacitance | $V_{G S}=0 ; V_{D S}=50 \mathrm{~V} ; \mathrm{f}=1 \mathrm{MHz}$ | - | 190 | - | pF |
| $\mathrm{C}_{\mathrm{rs}}$ | feedback capacitance | $V_{G S}=0 ; V_{D S}=50 \mathrm{~V} ; \mathrm{f}=1 \mathrm{MHz}$ | - | 14 | - | pF |
| $\mathrm{C}_{\mathrm{d}-\mathrm{f}}$ | drain-flange capacitance |  | - | 5.4 | - | pF |

$\mathbf{V}_{\mathrm{GS}}$ group indicator

| GROUP | LIMITS <br> (V) |  | GROUP | LIMITS <br> (V) |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  | MIN. | MAX. |  | MIN. | MAX. |
| A | 2.0 | 2.1 | O | 3.3 | 3.4 |
| B | 2.1 | 2.2 | P | 3.4 | 3.5 |
| C | 2.2 | 2.3 | Q | 3.5 | 3.6 |
| D | 2.3 | 2.4 | R | 3.6 | 3.7 |
| E | 2.4 | 2.5 | S | 3.7 | 3.8 |
| F | 2.5 | 2.6 | T | 3.8 | 3.9 |
| G | 2.6 | 2.7 | U | 3.9 | 4.0 |
| H | 2.7 | 2.8 | V | 4.0 | 4.1 |
| J | 2.8 | 2.9 | W | 4.1 | 4.2 |
| K | 2.9 | 3.0 | X | 4.2 | 4.3 |
| L | 3.0 | 3.1 | Y | 4.3 | 4.4 |
| M | 3.1 | 3.2 | Z | 4.4 | 4.5 |
| N | 3.2 | 3.3 |  |  |  |


[^0]:    i. Semi-Conductors reserves the right to change test conditions, parameter limits and packuge dimensions without notice Information furmished by NJ Semi-Conductors is believed to be both accurate and reliable all the lime of guing to press. However w
     astemers to wetit hat thasheets ore current before placing wriers

